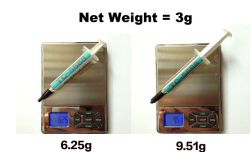




Dow Corning TC-5688 Thermally Conductive Compound (3.5g) - 8.0w/m.k

\$19.99 As low as
\$18.99

Product Images



Description

Dow Corning®TC-5688 Thermally Conductive Compound was developed exclusively for Intel microprocessors in collaboration with the Intel Mobile Platforms Group. TC-5688 was developed and optimized for multi-chip packages and employs a proprietary formula of advanced silicone polymers that interacts with thermally conductive filler particles to form a matrix that is highly resistant to pump-out and other common failure

mechanisms. The result is a thermal compound that delivers extreme performance and exceptional reliability for the thermal interface needs.

Note: This Item can not be shipped using DHL

Features

- Low thermal resistance for superior heat transfer, 0.061cm²C/W @40 PSI
- Thin bond line for hi-efficiency conductivity
- Enhance cooling performance
- Non pressure dependent
- Multi-language instructions included
- RoHS compliant
- AMD recommended

Specifications

0

Additional Information

Brand	ModDIY
SKU	MDY-TC-5688
Weight	0.0100
TIM Type	Paste

